

## Electronic Supporting Information (ESI)

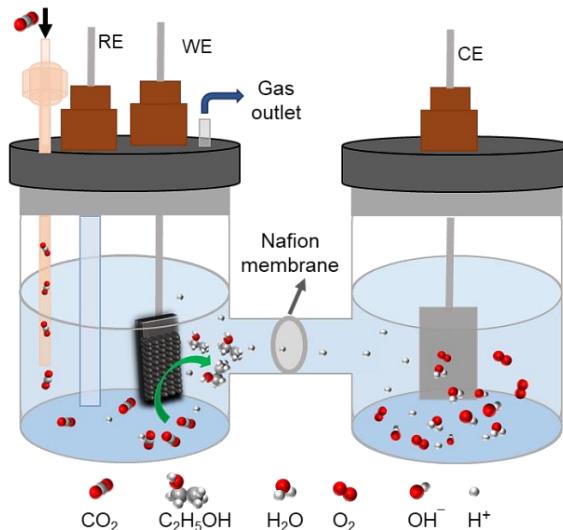
### Fractal growth of fern-like nanostructured Cu<sub>2</sub>O film electrode for electrochemical reduction of CO<sub>2</sub> to ethanol

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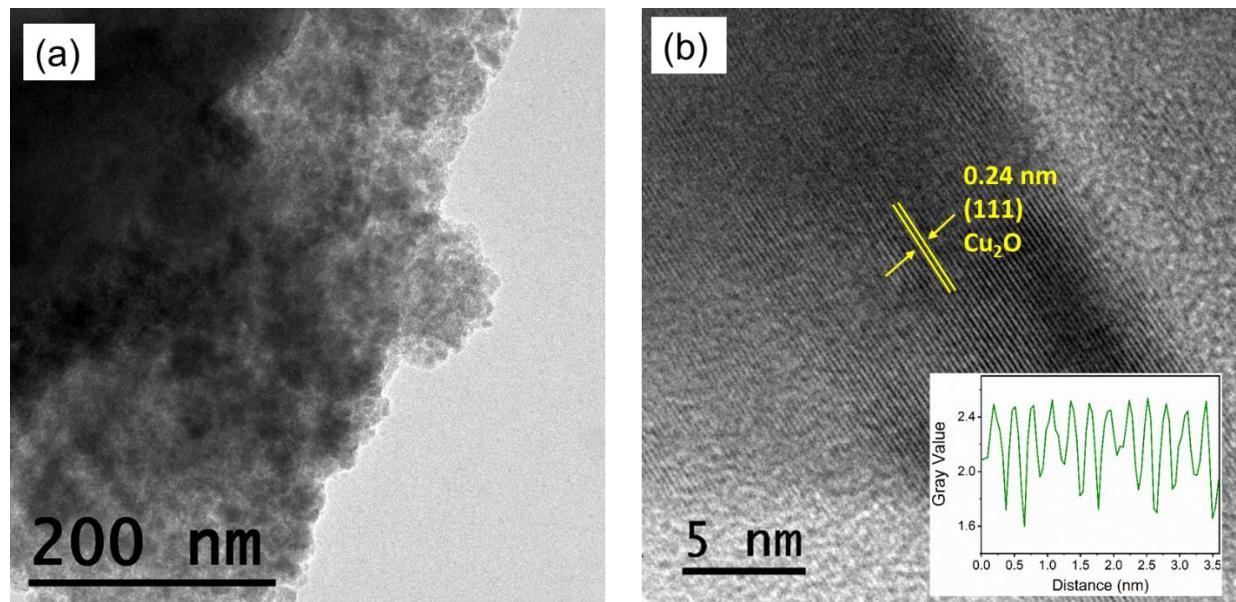
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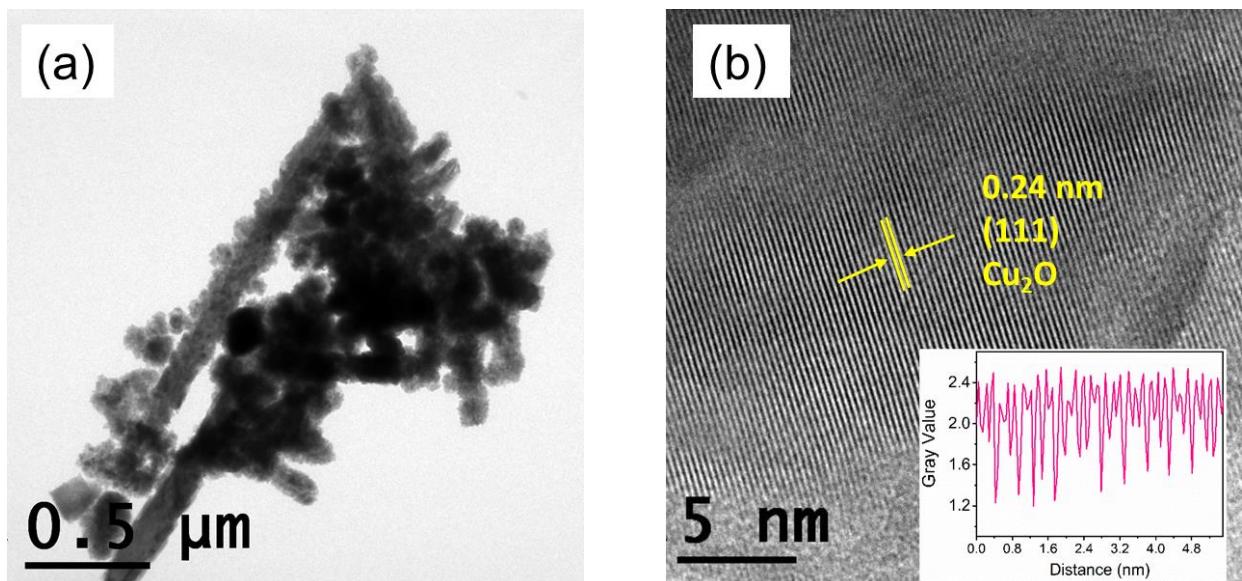
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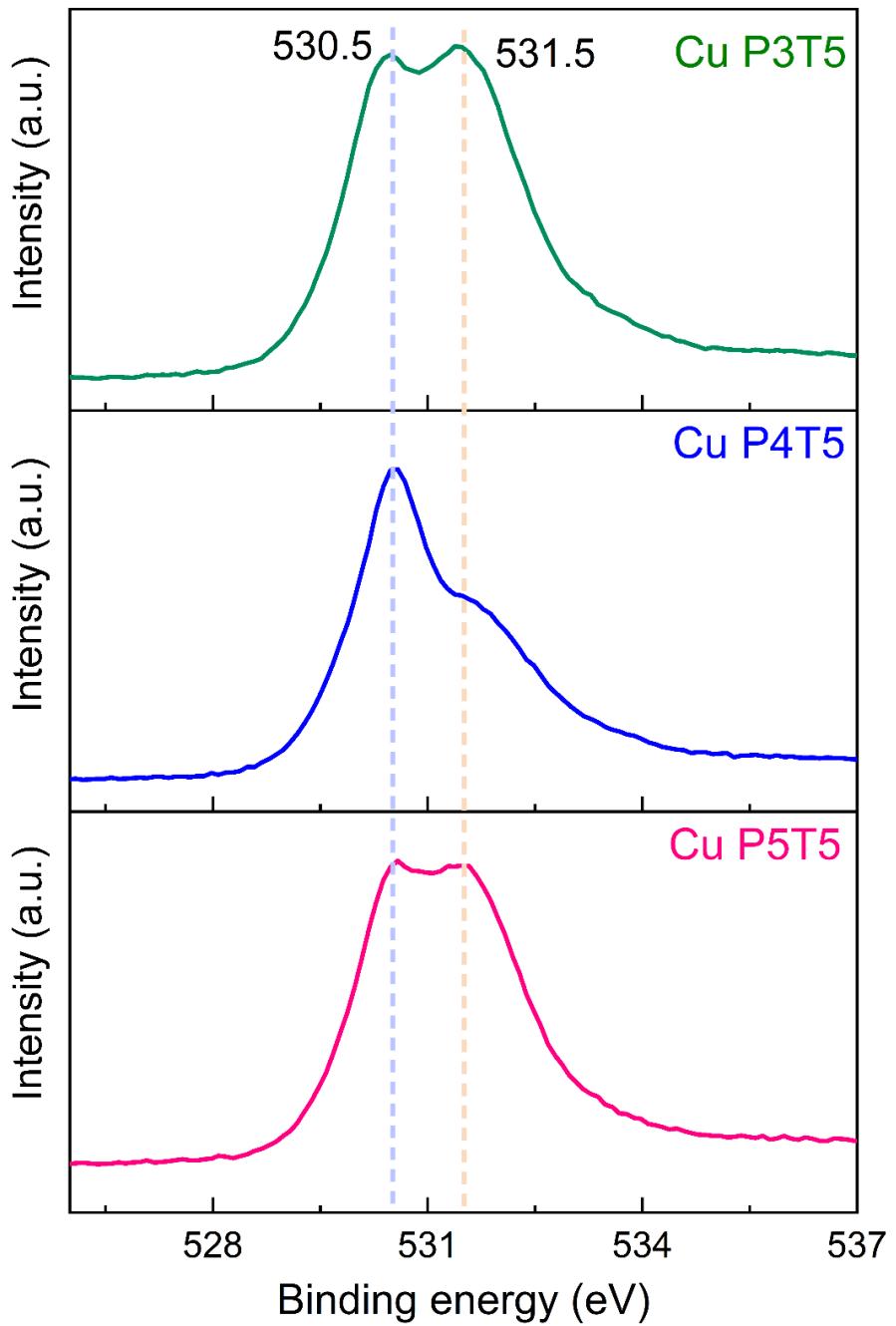
**Scheme S1.** Schematic diagram of the electrochemical setup (H-cell) used to carry out electrochemical CO<sub>2</sub> reduction.



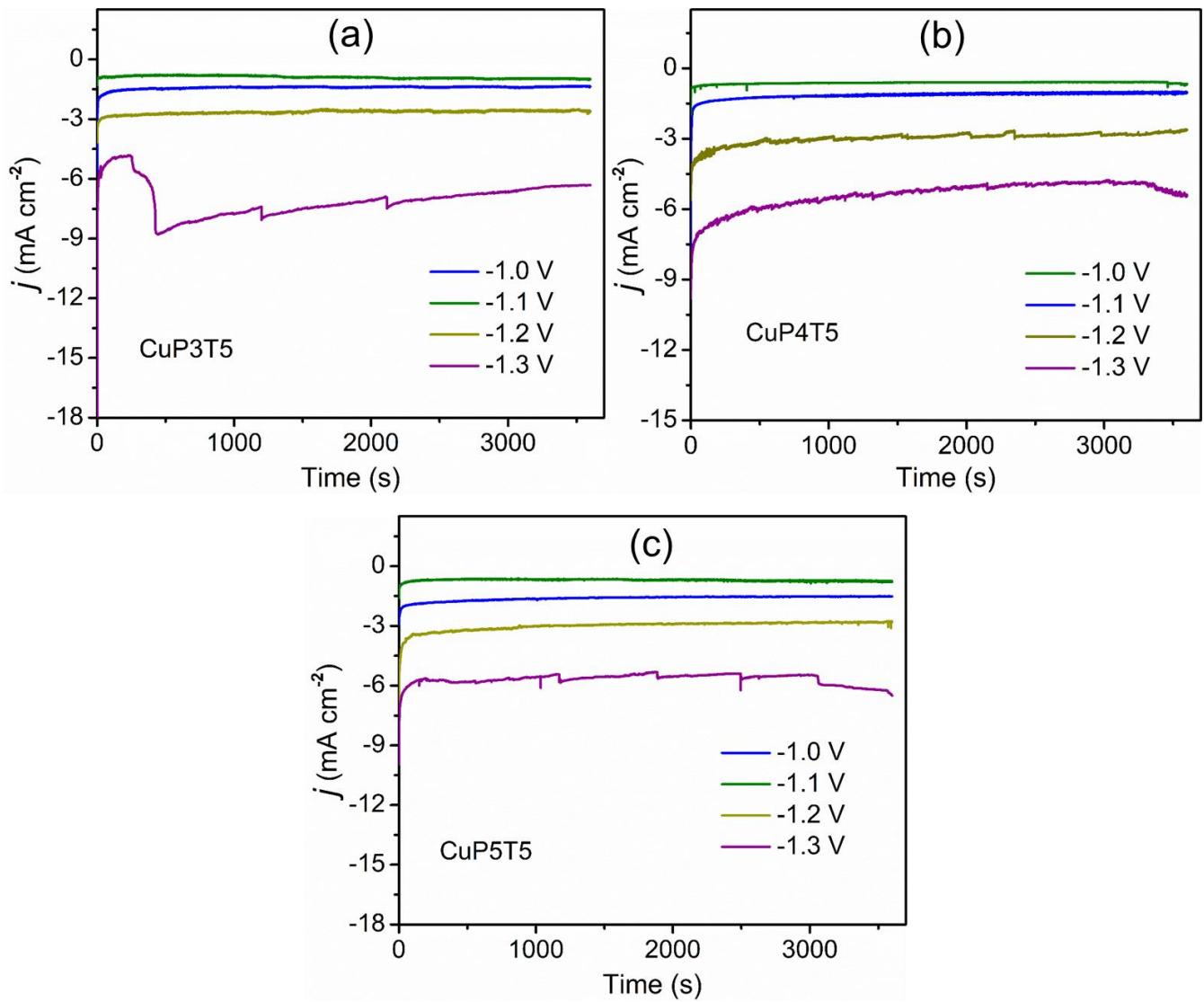
**Figure S1.** HR-TEM images of CuP3T5 at different magnifications.



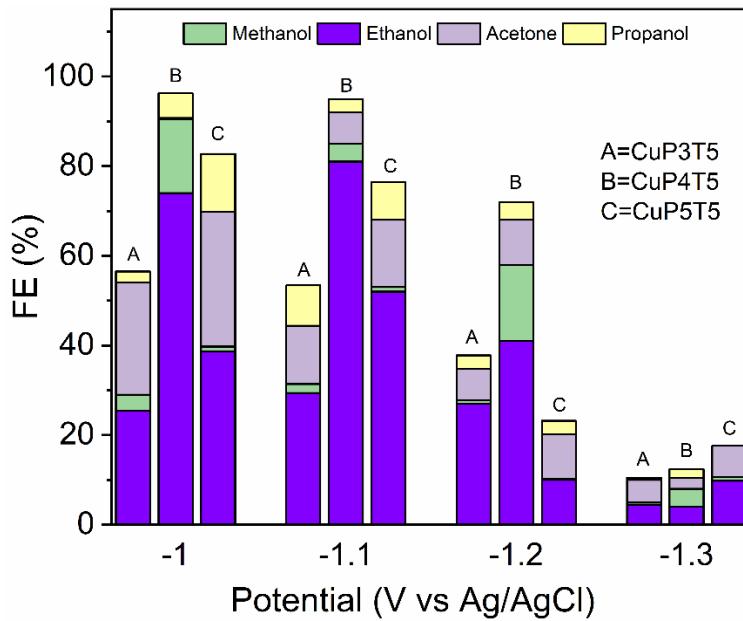
**Figure S2.** HR-TEM images of CuP5T5 at different magnifications.



**Figure S3.** Core level O 1s XPS spectra of CuP3T5, CuP4T5 and CuP5T5 electrodes.



**Figure S4.** Chronoamperometry performances of CuP3T5, CuP4T5 and CuP5T5 film electrodes at the various applied potential of -1.0 to -1.3 V for 1 hour in  $\text{CO}_2$  saturated 0.1 M  $\text{KHCO}_3$  electrolyte.



**Figure S5.** Faradaic efficiecies given by of CuP3T5, CuP4T5 and CuP5T5 film electrodes at the various applied potenials of -1.0 to -1.3 V in CO<sub>2</sub> saturated 0.1 M KHCO<sub>3</sub> electrolyte.

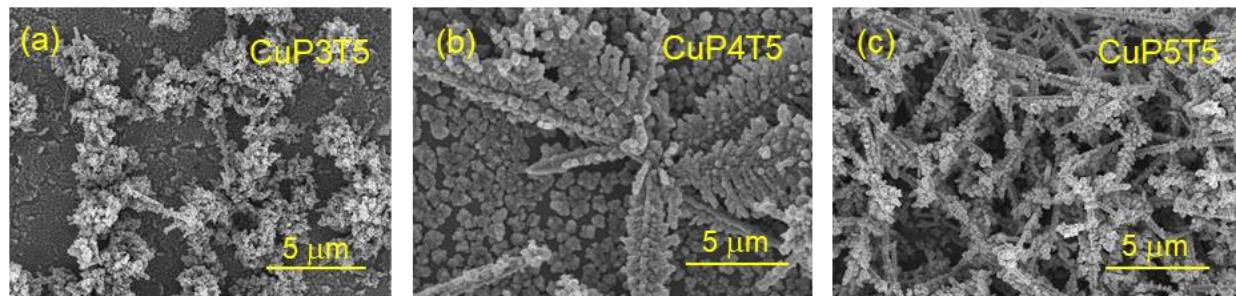
**Table S1.** Faradaic efficiecies obtained by applying 1h chronoamperometry.

Electro-deposited Materials	Potential V vs Ag/AgCl	Faradaic Efficiencies (%)			
		Ethanol	Methanol	Acetone	propanol
CuP3T5	-1.0	25.5	3.5	25	2.5
	-1.1	29.4	2	13	9
	-1.2	27	0.8	7	3
	-1.3	4.5	0.5	5	0.5
CuP4T5	-1.0	74	16.5	0.23	5.5
	-1.1	80	4	7	3
	-1.2	41	17	10	4
	-1.3	4	4	2.4	2
CuP5T5	-1.0	38.6	1.15	30	13
	-1.1	51	1	15	8.5
	-1.2	10	0.2	10	3
	-1.3	9.8	0.8	7	0

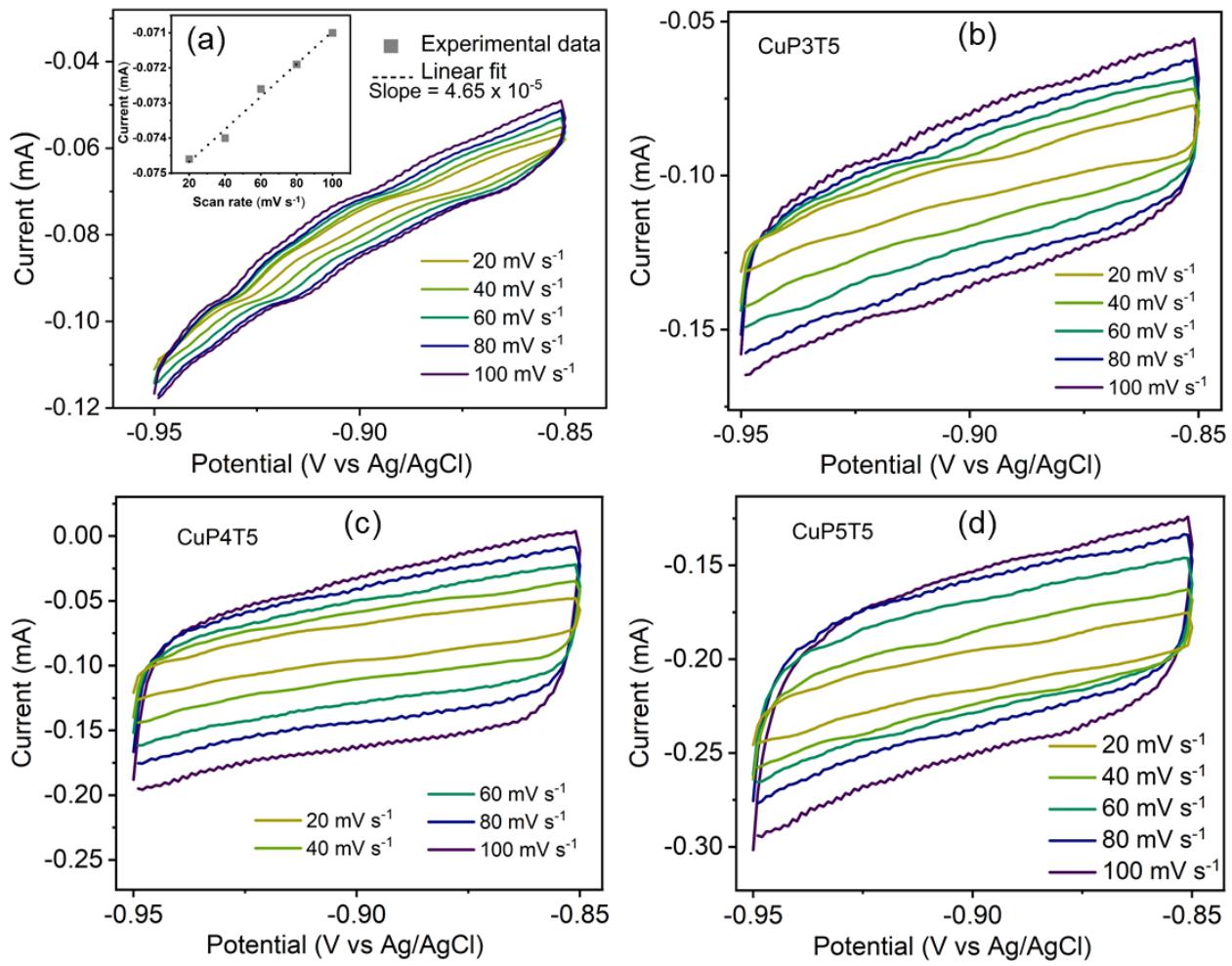
Calculation of the Faradaic efficiency:

$$FE = \frac{n \times F \times C_i \times V_i}{j \times A \times t} \times 100$$

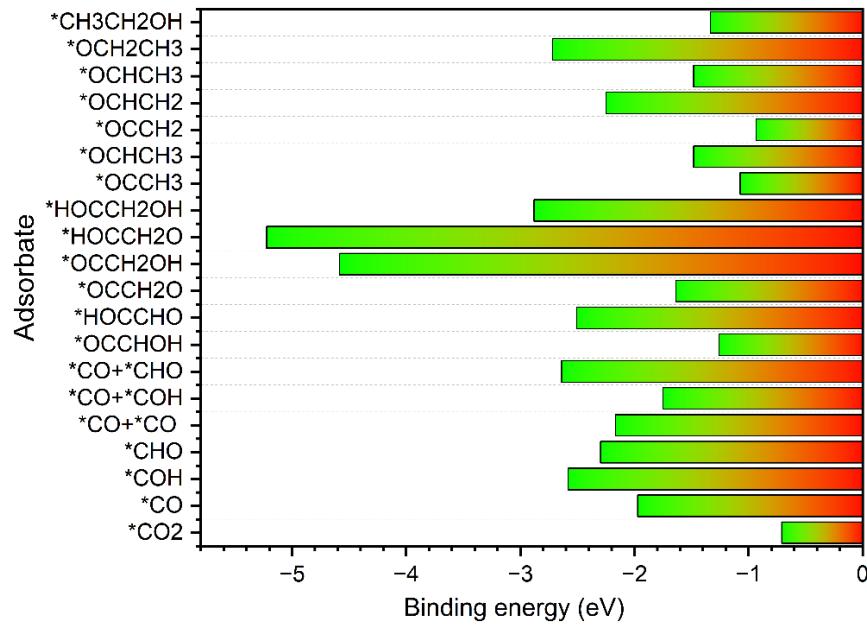
where, n is the number of electrons, F is the Faraday constant (96485, C/mol), C<sub>i</sub> is the concentration of the product in mol/L, V<sub>i</sub> is volume of the catholyte in L, j=total current density in A/cm<sup>2</sup>, A= area of the electrode in cm<sup>2</sup> and t is time in seconds.



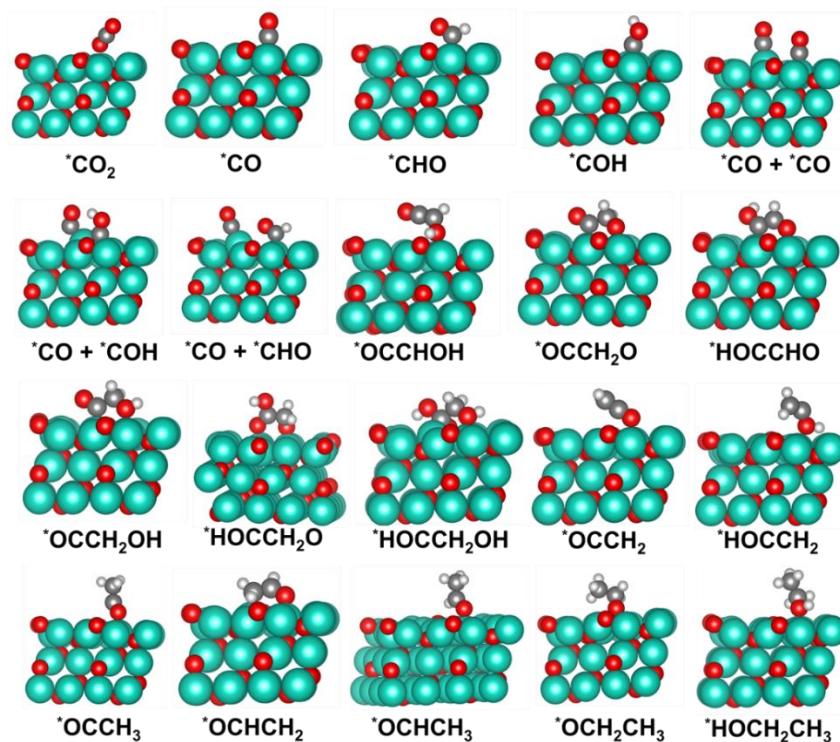
**Figure S6.** HR-SEM images of the film electrodes recorded after the electrochemical studies.



**Figure S7.** CV curves in the non-faradaic region at different scan rates of 20, 40, 60, 80 and 100 mV s<sup>-1</sup> for (a) bare SS-316 with fitted graph, (b) CuP3T5, (c) CuP4T5 and (d) CuP5T5 film electrodes in 0.1 M KHCO<sub>3</sub> electrolyte.



**Figure S8.** The adsorption binding energy of the intermediates on the surface of Cu<sub>2</sub>O(111).



**Figure S9.** The energy-minimized structures that represent the different intermediates involved in the conversion of CO<sub>2</sub> to C<sub>2</sub>H<sub>5</sub>OH. The atoms are represented by the color codes Cu-cyan, O-red, C-grey, and H-white. Note: \*adsorbed intermediate.

**Table S2.** An overview of faradaic efficiencies reported using Cu<sub>2</sub>O based catalysts in electrochemical CO<sub>2</sub> reduction.

Preparation method	Sample	Substrate	Electrolyte	Product, FE (%)	E vs RHE or (Ag/AgCl)	Ref.
Galvanostatic deposition	Cu <sub>2</sub> O	Cu disc	0.1 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 40 C <sub>2</sub> H <sub>5</sub> OH, 16	-0.99	[1]
Electrodeposition	Cu <sub>2</sub> O inverse opals	FTO film	0.1 M KHCO <sub>3</sub>	CO, 45.3 HCOOH, 34.5	-0.6 -0.8	[2]
Wet chemical reduction method	Cu <sub>2</sub> O nanoparticles (NPs)	Glassy carbon electrode	0.5 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 59	-1.1	[3]
Electro-redeposition	Cu <sub>2</sub> (OH) <sub>3</sub> Cl sol-gel	Carbon paper	0.1 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 38.5 CH <sub>4</sub> , 0.03	-1.2	[4]
Electrodeposition	Cu <sub>2</sub> O-derived Cu NPs	Cu plate	0.1 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 33.5 CH <sub>4</sub> , 4.0	-1.1	[5]
Electrodeposition	Mesoporous Cu <sub>2</sub> O	Cu foam	0.5 M NaHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 37	-0.7	[6]
One-pot wet-chemical	Cu <sub>2</sub> O NPs/C	Glassy carbon electrode	0.1 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 57.3	-1.1	[7]
Precipitation	multihollow Cu <sub>2</sub> O	Hydrophobic carbon paper	2 M KOH	C <sub>2</sub> H <sub>4</sub> , 38 CH <sub>3</sub> COOH, 4.8 C <sub>2</sub> H <sub>5</sub> OH, 26.9 C <sub>3</sub> H <sub>7</sub> OH, 5.5	-0.61	[8]
Template-assisted hydrothermal synthesis process.	Cu <sub>2</sub> O-octahedral	Carbon paper	0.5 M KHCO <sub>3</sub>	CH <sub>3</sub> OH, 4.9 C <sub>2</sub> H <sub>5</sub> OH, 17.9 C <sub>3</sub> H <sub>8</sub> O, 12.6	-0.3	[9]
In-situ etching methods	Cu <sub>2</sub> O@Cu-MOF	Glassy carbon electrode	0.1 M KHCO <sub>3</sub>	CO, 1.8 CH <sub>4</sub> , 63.2 C <sub>2</sub> H <sub>4</sub> , 16.2 HCOOH, 3.8 C <sub>2</sub> H <sub>5</sub> OH, 4.1	-1.71	[10]
Ion-track technology	Cu nanowire networks	Cu back electrode in touched with Cu plate	0.1 M KHCO <sub>3</sub>	CH <sub>4</sub> , ~0.3 C <sub>2</sub> H <sub>4</sub> , ~5 C <sub>2</sub> H <sub>6</sub> , ~2 C <sub>2</sub> H <sub>5</sub> OH, ~1.5 C <sub>3</sub> H <sub>7</sub> OH, ~3 C <sub>2</sub> H <sub>6</sub> O <sub>2</sub> , ~4 CH <sub>3</sub> COOH, ~0.3	-0.83	[11]
Combined Phase inversion/sintering	Cu <sub>2</sub> O over Cu hollow fiber	Copper tube	0.5 M KHCO <sub>3</sub>	HCOOH, 92.3	-1.18	[12]
In-situ reconstructions	Cu/Cu <sub>2</sub> O nanoclusters	--	0.1 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>4</sub> , 70.2	-1.03	[13]
Wet chemical method	Cu/Cu <sub>2</sub> O nanocrystal	Hydophobic carbon paper	0.1 M K <sub>2</sub> SO <sub>4</sub>	C <sub>2</sub> H <sub>4</sub> , 38 C <sub>2</sub> H <sub>5</sub> OH, 30	-2.0 vs Ag/AgCl	[14]
Electrodeposition	Cu <sub>2</sub> O (CuP4T5)	Stainless steel-316	0.1 M KHCO <sub>3</sub>	C <sub>2</sub> H <sub>5</sub> OH, ~80 CH <sub>3</sub> OH, ~4 Acetone, ~7 Propanol, ~3	-1.1 vs Ag/AgCl	This work

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